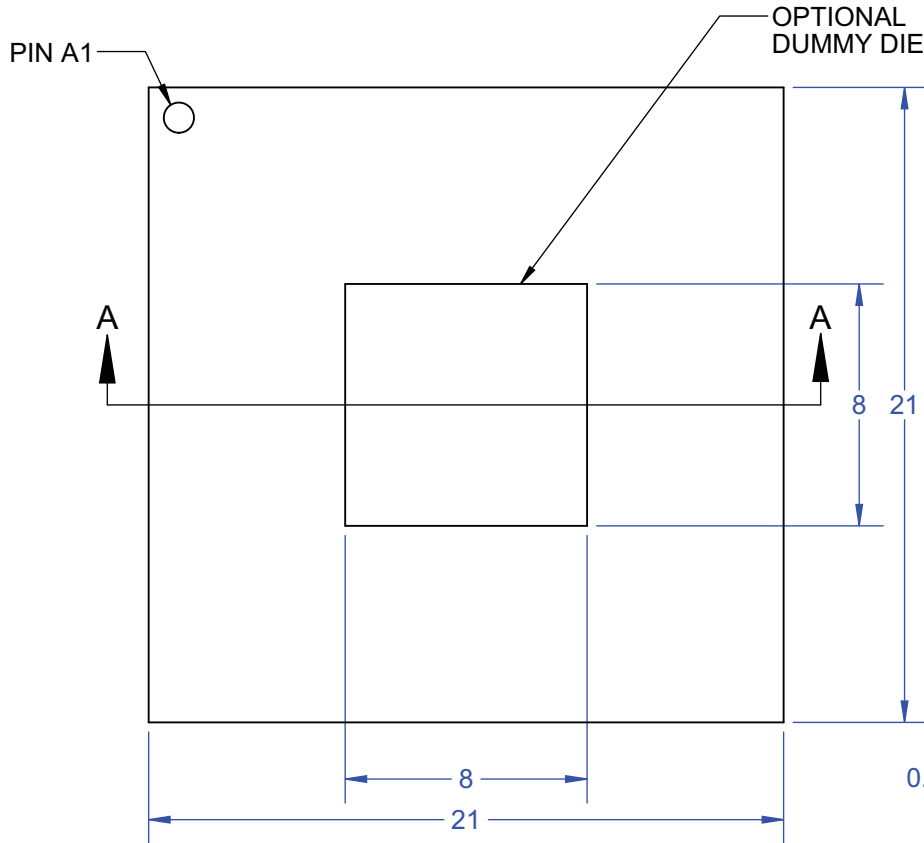
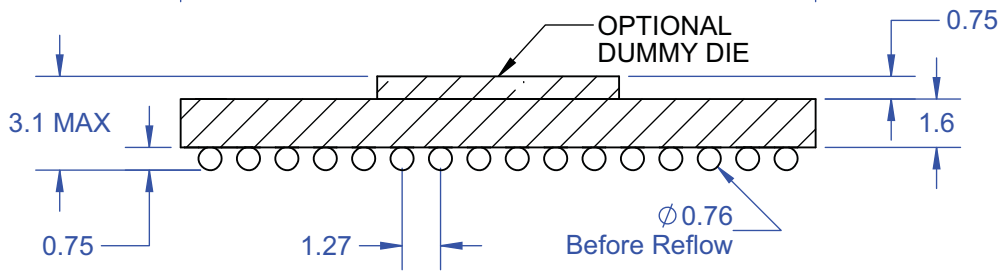
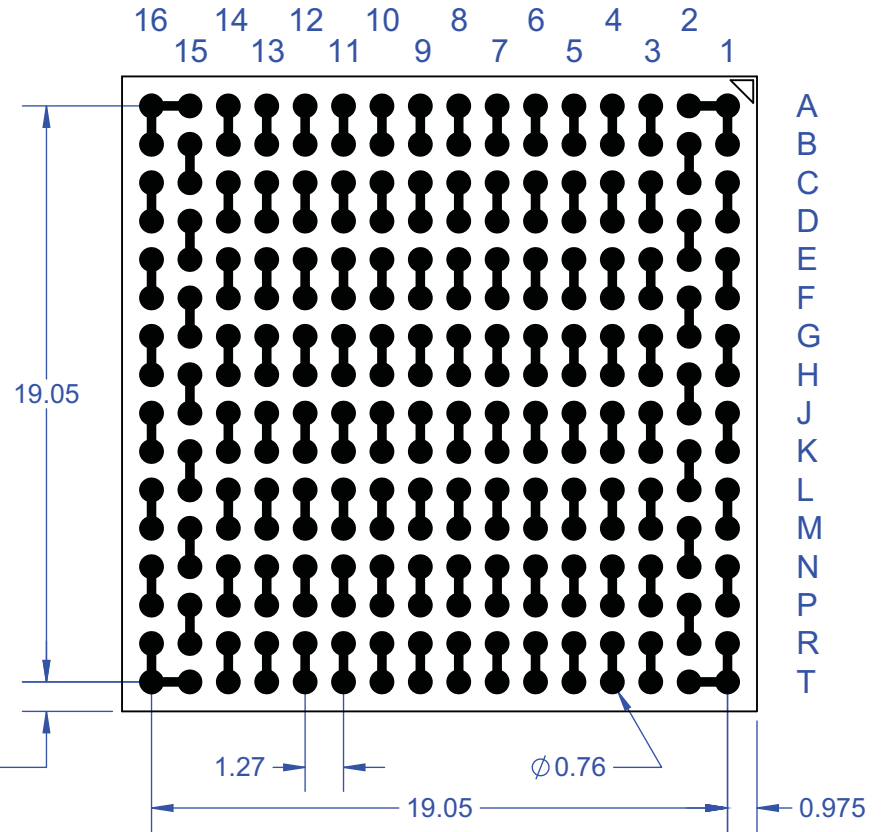


TOP VIEW



BALL VIEW



SECTION A-A

Notes: (Unless Otherwise Specified).

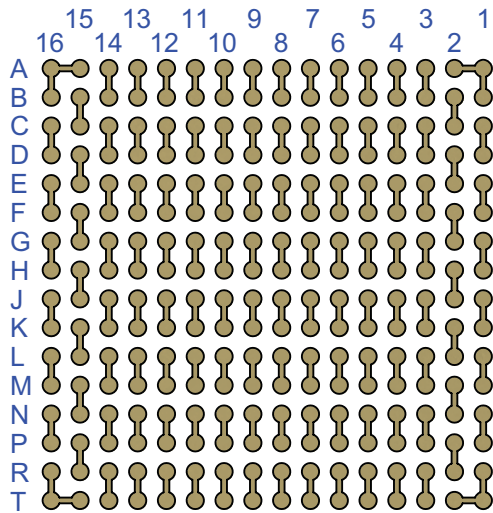
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.762mm (30 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.610mm (24 MIL).
- 5) PAD Cu DIAMETER: 0.838mm (33 MIL).
- 6) SUBSTRATE MATERIAL: FR4.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

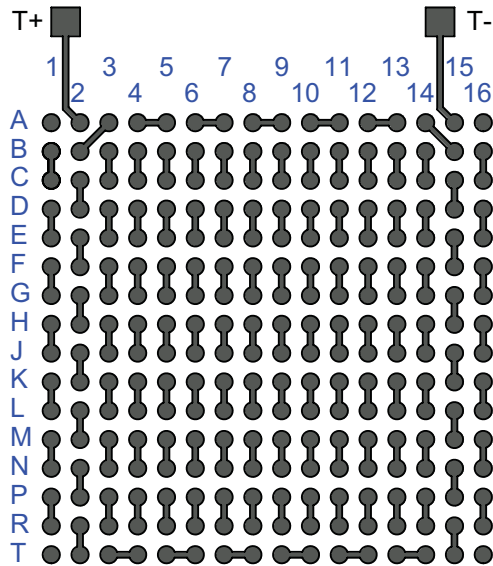
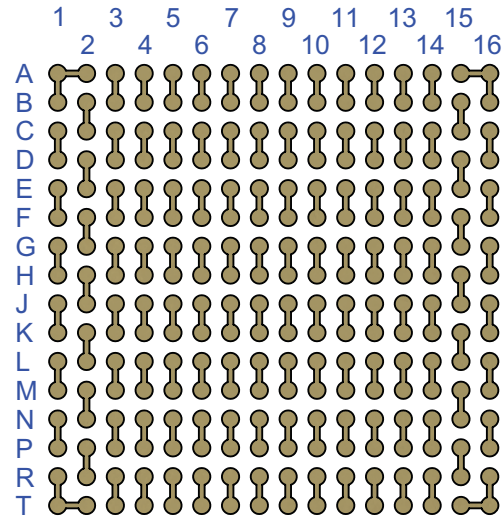
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LBGA256T1.27C-DC61	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA256T1.27C-DC61D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA256T1.27-DC61	Sn63/Pb37	NO	NO	NO
LBGA256T1.27-DC61D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE	TopLine®			
DRAWN T. Au	12/25/15				
ENG M. Hart	12/25/15	TITLE LBGA256T1.27C-DC61 DAISY CHAIN DUMMY			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		2:1	A	526101	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

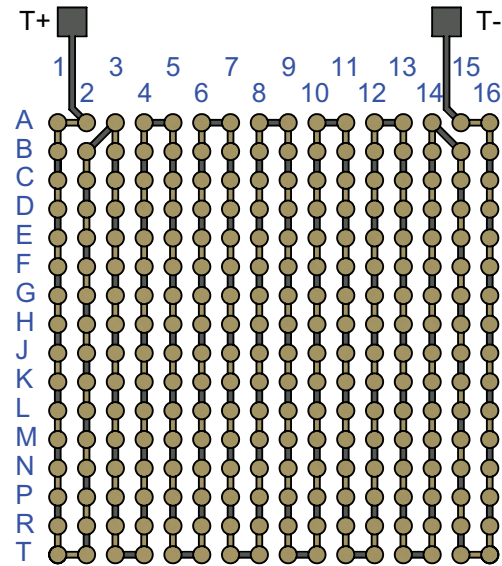
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

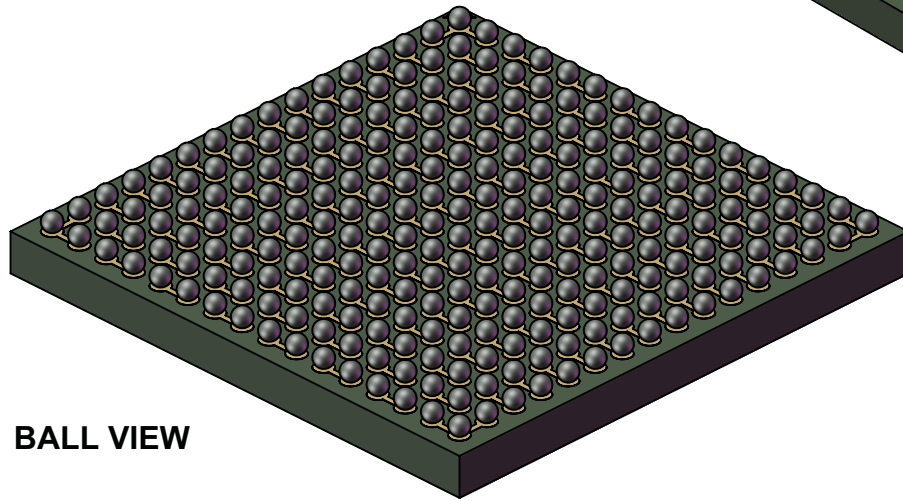
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTD ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.838mm [33 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.254mm [10 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.61mm [24 MIL].

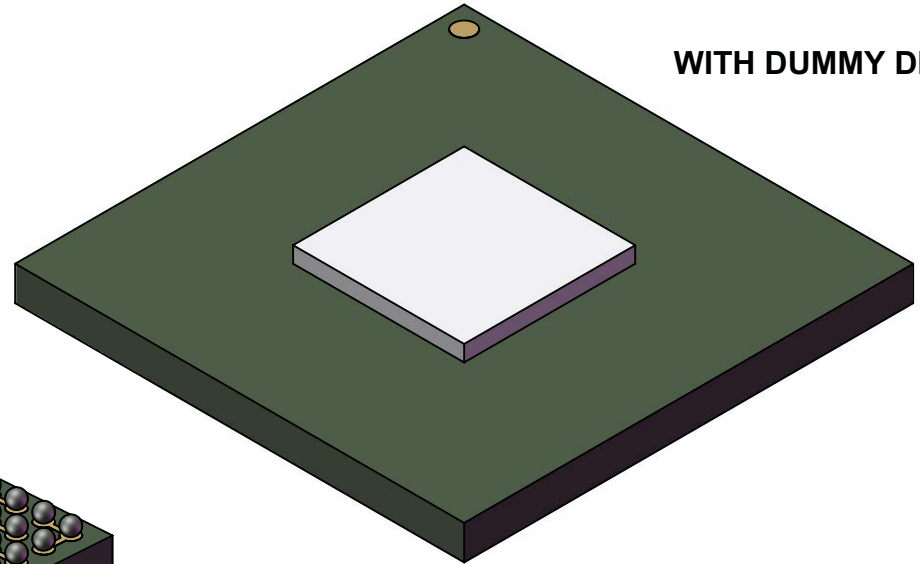


TITLE			
LPGA256T1.27C-DC61 DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
3:2	A	526101	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

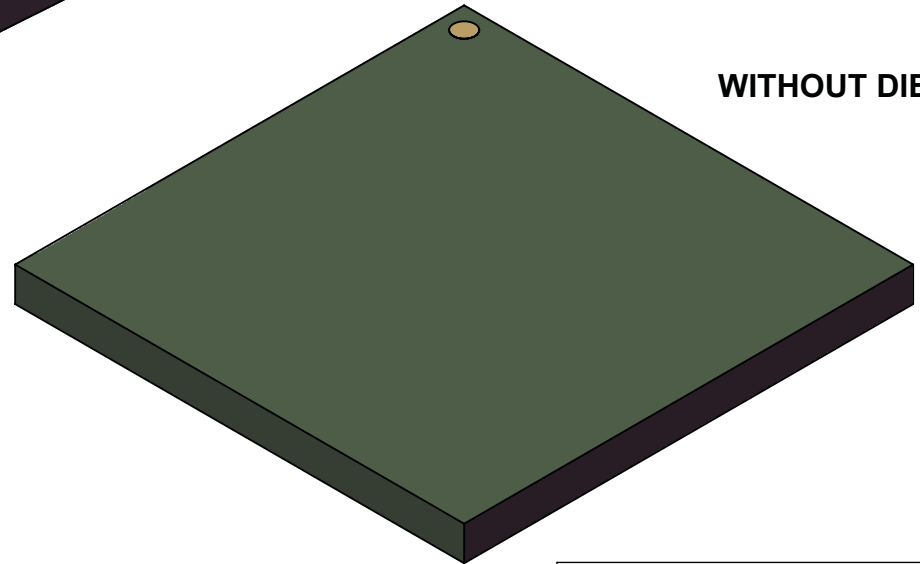
MODEL



BALL VIEW



WITH DUMMY DIE



WITHOUT DIE

TopLine[®]

TITLE LBGA256T1.27C-DC61
DAISY CHAIN DUMMY

SCALE 2:1	SIZE A	DRAWING NO. 526101	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3